

REMARKS

Reconsideration and allowance of the above-referenced application are respectfully requested.

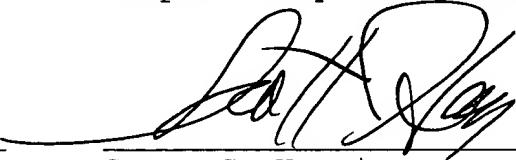
In view of the above amendments and remarks, therefore, all of the claims should be in condition for allowance. A formal notice to that effect is respectfully solicited.

Applicants would like to bring to the attention of the Examiner the reference listed on the attached form PTO-1449. Consideration and return of a copy of the enclosed form with the Examiner's initials are solicited.

Please apply any charges or credits to Deposit Account No. 06-1050.

Respectfully submitted,

Date: 10/10/02

  
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VERSION TO SHOW CHANGES MADE

In the Claims:

The claims have been amended as follows.

1. (Amended) A method of manufacturing a display device, comprising [the steps of]:

forming a peeling layer on [an element-forming] a first substrate;

forming an insulating layer on said peeling layer;

forming a [luminous] light emitting element on said insulating layer;

bonding a [fixed] second substrate [on] over said [luminous] light emitting element by using a first adhesive;

exposing [the entire substrate] the peeling layer to a gas containing halogen fluoride after bonding said [fixed] second substrate to thereby remove said peeling layer and the first substrate; and

bonding a [bonding] third substrate to said insulating layer by using a second adhesive.

2. (Amended) A method according to claim 1, wherein said first adhesive is selected from the group consisting of

polyimide, acrylic, [or] and epoxy resin [is used as said first adhesive].

3. (Amended) A method according to claim 1, wherein [a material used for forming said bonding substrate is the same as that for forming said fixed substrate] the third substrate comprises the same material as the second substrate.

4. (Amended) A method of manufacturing a display device, comprising [the steps of]:

forming a peeling layer on [an element-forming] a first substrate;

forming an insulating layer on said peeling layer;

forming a semiconductor element on said insulating layer;

forming at least one interlayer insulating film over the semiconductor element;

forming a [luminous] light emitting element [that is] over the interlayer insulating film, the light emitting element electrically connected to said semiconductor element;

bonding a [fixed] second substrate [on] over said [luminous] light emitting element by using a first adhesive;

exposing [the entire substrate] the peeling layer to a gas containing halogen fluoride after bonding said [fixed] second

substrate to thereby remove said peeling layer and first substrate; and

bonding a [bonding] third substrate to said insulating layer by using a second adhesive.

5. (Amended) A method according to claim 4, wherein said first adhesive is selected from the group consisting of polyimide, acrylic, [or] and epoxy resin [is used as said first adhesive].

6. (Amended) A method according to claim 4, wherein [a material used for forming said bonding substrate is the same as that for forming said fixed substrate] the third substrate comprises the same material as the second substrate.

New claims 16-43 have been added.